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<div>LAYER STACK UP: REFERENCE ONLY</div> <div>ALL LAYERS: 1 ounce Cu (1.4 mils)</div> <table><thead><tr><th>Layer</th><th>Name</th><th>Material</th><th>Thickness</th><th>Constant</th><th>Board Layer Stack</th></tr></thead><tbody><tr><td></td><td>Top Overlay</td><td></td><td></td><td></td><td></td></tr><tr><td></td><td>Top Solder</td><td>Solder Resist</td><td>0.40mil</td><td>3.5</td><td></td></tr><tr><td>1</td><td>Top Layer</td><td></td><td>1.40mil</td><td></td><td></td></tr><tr><td></td><td>Dielectric 1</td><td>FR-4 High Tg</td><td>7.00mil</td><td>4.2</td><td></td></tr><tr><td>2</td><td>Signal Layer 1</td><td></td><td>1.40mil</td><td></td><td></td></tr><tr><td></td><td>Dielectric 2</td><td>FR-4 High Tg</td><td>41.00mil</td><td>4.2</td><td></td></tr><tr><td>3</td><td>Signal Layer 2</td><td></td><td>1.40mil</td><td></td><td></td></tr><tr><td></td><td>Dielectric 3</td><td>FR-4 High Tg</td><td>7.00mil</td><td>4.2</td><td></td></tr><tr><td>4</td><td>Bottom Layer</td><td></td><td>1.40mil</td><td></td><td></td></tr><tr><td></td><td>Bottom Solder</td><td>Solder Resist</td><td>0.40mil</td><td>3.5</td><td></td></tr><tr><td></td><td>Bottom Overlay</td><td></td><td></td><td></td><td></td></tr><tr><td colspan="3">Total board thickness:</td><td colspan="3">61.40mil</td></tr></tbody></table> <table><thead><tr><th>Symbol</th><th>Quantity</th><th>Finished Hole Size</th><th>Plated</th><th>Hole Type</th><th>Drill Layer Pair</th><th>Hole Tolerance</th></tr></thead><tbody><tr><td>▽</td><td>21</td><td>10,00mil (0,254mm)</td><td>PTH</td><td>Round</td><td>Top Layer - Bottom Layer</td><td></td></tr><tr><td>☆</td><td>2</td><td>24,00mil (0,610mm)</td><td>PTH</td><td>Round</td><td>Top Layer - Bottom Layer</td><td></td></tr><tr><td>□</td><td>8</td><td>40,16mil (1,020mm)</td><td>PTH</td><td>Round</td><td>Top Layer - Bottom Layer</td><td></td></tr><tr><td></td><td>31 Total</td><td></td><td></td><td></td><td></td><td></td></tr></tbody></table> <div><div>800.00</div><div>1000.00</div></div> <div><div>1000.00mil</div></div>												Layer	Name	Material	Thickness	Constant	Board Layer Stack		Top Overlay						Top Solder	Solder Resist	0.40mil	3.5		1	Top Layer		1.40mil				Dielectric 1	FR-4 High Tg	7.00mil	4.2		2	Signal Layer 1		1.40mil				Dielectric 2	FR-4 High Tg	41.00mil	4.2		3	Signal Layer 2		1.40mil				Dielectric 3	FR-4 High Tg	7.00mil	4.2		4	Bottom Layer		1.40mil				Bottom Solder	Solder Resist	0.40mil	3.5			Bottom Overlay					Total board thickness:			61.40mil			Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance	▽	21	10,00mil (0,254mm)	PTH	Round	Top Layer - Bottom Layer		☆	2	24,00mil (0,610mm)	PTH	Round	Top Layer - Bottom Layer		□	8	40,16mil (1,020mm)	PTH	Round	Top Layer - Bottom Layer			31 Total						A		B		C		D	
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ALL ARTWORK VIEWED FROM TOP SIDE		BOARD #: BSR253		REV: A		SUN REV: Not in version control		Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.																																																																																																																												
LAYER NAME = Fabrication Drawing		TID #: N/A																																																																																																																																		
PLOT NAME = Fabrication Drawing		GENERATED : 10/26/2022 2:46:24 PM		TEXAS INSTRUMENTS																																																																																																																																
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DESIGN INFORMATION	
MIN. TRACK WIDTH: 10 MIL	
MIN. CLEARANCE: 6 MIL	
MIN. VIA PAD SIZE: 20 MIL	
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL	
PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL	
MATERIAL:	
<input type="checkbox"/> FR-408 <input checked="" type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER	
THICKNESS: <input checked="" type="checkbox"/> 62 MIL (1.6mm) +/-10% <input type="checkbox"/> OTHER	
TOLERANCE: <input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2	
<input type="checkbox"/> OTHER +/-	
BOW & TWIST: <input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2	
<input type="checkbox"/> OTHER +/-	
DRILLING:	
REFERENCE: <input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES	
PTH COPPER THICKNESS: <input checked="" type="checkbox"/> 20-30 um <input type="checkbox"/> OTHER	
BOARD FINISH:	
SILKSCREEN: <input checked="" type="checkbox"/> TOP <input checked="" type="checkbox"/> BOTTOM	
SILKSCREEN COLOR: <input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER	
SOLDER RESIST COLOR: <input checked="" type="checkbox"/> GREEN <input type="checkbox"/> OTHER	
<input checked="" type="checkbox"/> MATTE <input type="checkbox"/> SEMI-GLOSS	
SURFACE FINISH: <input checked="" type="checkbox"/> IMMERSION GOLD (ENIG) <input type="checkbox"/> ENEPIG	
<input type="checkbox"/> IMM. TIN/SILVER OR EQUIV <input type="checkbox"/> OTHER	
ARRAY/PANEL: <input type="checkbox"/> CUT AND TRIM PER M1 BOARD OUTLINE	
<input type="checkbox"/> N.C. ROUTE <input checked="" type="checkbox"/> V. SCORE	
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS -> <input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3	
<input checked="" type="checkbox"/> RoHS <input type="checkbox"/> OTHER PER ORDER	
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.	
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER	
ADDITIONAL REQUIREMENTS:	
MICROSECTION: <input type="checkbox"/> YES	
BARE BOARD ELEC. TEST: <input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER	
<input type="checkbox"/> XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE	
<input type="checkbox"/> XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE	
<input type="checkbox"/> OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE	
<input type="checkbox"/> LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE	
TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE	
<div><div></div><div>TEXAS INSTRUMENTS</div></div>	
PROJECT TITLE: TPSF12C3QEUW	
DESIGNED FOR: TBD	
FILE NAME: BSR253A.PcbDoc	
ENGINEER: Timothy Hegarty	LAYOUT BY: Tony Jacobs
SCALE: 1.00	ALTUM DESIGNER VERSION: 22.10.1.41